

**DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN
APPLICATION DATA SHEET (37 CFR 1.76)**

Electronic Version v11

Stylesheet Version v10

**Title of
Invention**

LIGHT EMITTING DIODE HAVING AN ADHESIVE LAYER AND A
MANUFACTURING METHOD THEREOF

As the below named inventors, we declare that:

This declaration is directed to the invention titled: " LIGHT EMITTING DIODE HAVING AN
ADHESIVE LAYER AND A MANUFACTURING METHOD THEREOF"

We believe that we are the original and first inventors of the subject matter which is claimed
and for which a patent is sought;

We have reviewed and understand the contents of the above-identified application, including
the claims, as amended by any amendment specifically referred to above;

We acknowledge the duty to disclose to the United States Patent and Trademark Office all
information known to us to be material to patentability as defined in 37 CFR 1.56, including for
continuation-in-part applications, material information which became available between the
filing date of the prior application and the national or PCT International filing date of the
continuation-in-part application.

All statements made herein of own knowledge are true, all statements made herein on
information and belief are believed to be true, and further that these statements were made
with the knowledge that willful false statements and the like are punishable by fine or
imprisonment, or both, under 18 U.S.C. 1001, and may jeopardize the validity of the
application or any patent issuing thereon.

FULL NAME OF INVENTORS:

Inventor 1: Min-Hsun Hsieh	Inventor
Signature :	Citizen of : TW
Inventor 2: Tzu-Feng Tseng	Inventor
Signature :	Citizen of : TW
Inventor 3: Wen-Huang Liu	Inventor

Signature :	Citizen of : TW	
Inventor 4: Ting-Wei Yeh	Inventor	
Signature :	Citizen of : TW	
Inventor 5: Jen-Shui Wang	Inventor	
Signature :	Citizen of : TW	

COMBINED DECLARATION AND POWER OF ATTORNEY

As a below named inventor , I hereby declare that :

I believe I am the sole (if only one name appears below) , or joint (if more than one name appears) , original and first inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled :

"LIGHT EMITTING DIODE HAVING AN ADHESIVE LAYER AND A MANUFACTURING METHOD THEREOF"

+ The specification for the above entitled invention is filed herewith.
The specification for the above entitled invention was filed previously
with application serial number: Filing Date:

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the patentability of the invention disclosed in this application in accordance with Title 37, Code of Federal Regulations, Section 1.56 (a). I further acknowledge the duty in any continuation-in-part application to disclose to the Patent and Trademark Office all information known to be material to the patentability of the invention disclosed in this application, as defined in 1.56, which became available to me between the filing date of the prior application and the filing date of this application.

PRIORITY CLAIM

There is no claim of priority

Claim of priority is based on the following:

Filing No. to Taiwan : 09/114587
Filing Date to Taiwan : 2003/7/15

POWER OF ATTORNEY

As a named inventor, I hereby appoint the following attorneys to prosecute this application and to transact all related business in the Patent and Trademark Office:

Winston Hsu	Registration# 41,526	WinstonHsu@naipo.com.tw
Mord Michael Lewis	Registration# 50,478	MikeLewis@naipo.com.tw

P.O. Box 506,
Merrifield, Virginia 22116,
U.S.A
TEL: (02)8923-7350

DECLARATION

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true, and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment or both under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued hereon.

Date:	<u>2/3 2003</u>	<u>Min-Hsun Hsieh</u>
	Printed Name:	Min-Hsun Hsieh
	Post Office Address:	No.48, Park Ave. II, Science-Based Industrial Park,
	and Residence	Hsin-Chu City, Taiwan, R.O.C.
	Citizen of:	R.O.C.
Date:	<u>7/3 2003</u>	<u>Tzu-Feng Tseng</u>
	Printed Name:	Tzu-Feng Tseng
	Post Office Address:	No.48, Park Ave. II, Science-Based Industrial Park,
	and Residence	Hsin-Chu City, Taiwan, R.O.C.
	Citizen of:	R.O.C.
Date:	<u>7.3. 2003</u>	<u>Wen-Huang Liu</u>
	Printed Name:	Wen-Huang Liu
	Post Office Address:	No.48, Park Ave. II, Science-Based Industrial Park,
	and Residence	Hsin-Chu City, Taiwan, R.O.C.
	Citizen of:	R.O.C.
Date:	<u>7.3. 2003</u>	<u>Ting-Wei Yeh</u>
	Printed Name:	Ting-Wei Yeh
	Post Office Address:	No.48, Park Ave. II, Science-Based Industrial Park,
	and Residence	Hsin-Chu City, Taiwan, R.O.C.
	Citizen of:	R.O.C.
Date:	<u>7.3. 2003</u>	<u>Jen-Shui Wang</u>
	Printed Name:	Jen-Shui Wang
	Post Office Address:	No.48, Park Ave. II, Science-Based Industrial Park,
	and Residence	Hsin-Chu City, Taiwan, R.O.C.
	Citizen of:	R.O.C.